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#### INTERNATIONAL PRELIMINARY EXAMINATION REPORT

(PCT Article 36 and Rule 70)

Applicant's or agent's file reference		See Notification	on of Transmittal of International			
30794108WO01	FOR FURTHER ACTION	Preliminary Examination Report (Form PCT/IPEA/416)				
International application No.	International filing date (day/mo	nth/year)	Priority date (day/month/year)			
PCT/US03/39211	09 December 2003 (09.12.2003)	•				
International Patent Classification (IPC)	der to the second secon					
IPC(7): H01L 21/465, 29/06, 29/20, 33/	/00 and US Cl.: 257/98, 103; 438	3/43, 47				
Applicant						
FUJII ET AL.						
1. This international preliminary examination report has been prepared by this International Preliminary Examining Authority and is transmitted to the applicant according to Article 36.						
2. This REPORT consists of	a total of sheets, including	inis cover snee	et.			
This report is also accompanied by ANNEXES, i.e., sheets of the description, claims and/or drawings which have been amended and are the basis for this report and/or sheets containing rectifications made before this Authority (see Rule 70.16 and Section 607 of the Administrative Instructions under the PCT).						
These annexes consist of a	total of 5 sheets.					
	ations relating to the following	items:				
I Basis of the repo	I Basis of the report					
II Priority						
III Non-establishme	ent of report with regard to nov	velty, inventive	step and industrial applicability			
IV Lack of unity of						
V Reasoned statem	V Reasoned statement under Article 35(2) with regard to novelty, inventive step or industrial					
applicability; cit	applicability; citations and explanations supporting such statement					
VI Certain docume	VI Certain documents cited					
VII Certain defects i	VII Certain defects in the international application					
VIII Certain observations on the international application						
·						
Date of submission of the demand	Date	of completion of	of this report			
2 ato of sasimission of the demand		Date of completion of this report				
23 May 2005 (23.05.2005)		01 December 2005 (01.12.2005)				
Name and mailing address of the IPEA/US  Mail Stop PCT, Attn: IPEA/ US		Authorized officer				
Commissioner for Patents P.O. Box 1450	Tom	Thomas	MAMUSELAUNC			
Alexandria, Virginia 22313-1450 Facsimile No. (571) 273-3201	Telepl	ے hone No. 571-27				
Form PCT/IPEA/409 (cover sheet)(July 1998)						

#### INTERNATIONAL PRELIMINARY EXAMINATION REPORT

International application No.
PCT/US03/39211

I.	Basi	is of the report							
1.	With	ith regard to the elements of the international application:*							
		the international application as originally filed.							
	$\boxtimes$	the description:							
	···_	pages 2-15 as originally filed							
		pages NONE, filed with the demand							
		pages 1, filed with the letter of 13 October 2005 (13.10.2005)							
		the claims:							
		pages NONE, as originally filed pages 16-18/1, as amended (together with any statement) under Article 19							
		pages 10-1071, as amended (together with any statement) under Article 19 pages NONE, filed with the demand							
		pages NONE, filed with the letter of							
	X	the drawings:							
		pages 1-10 , as originally filed							
		pages NONE, filed with the demand							
,	[ <u>-</u> 1	pages NONE, filed with the letter of							
		the sequence listing part of the description:							
		pages NONE, as originally filed							
		pages NONE, filed with the demand pages NONE, filed with the letter of							
2.	With	h regard to the language, all the elements marked above were available or furnished to this Authority in the							
		uage in which the international application was filed, unless otherwise indicated under this item.							
	Thes	se elements were available or furnished to this Authority in the following language which is:							
		the language of a translation furnished for the purposes of international search (under Rule23.1(b)).							
		the language of publication of the international application (under Rule 48.3(b)).							
		the language of the translation furnished for the purposes of international preliminary examination(under Rules							
		55.2 and/or 55.3).							
3.		regard to any nucleotide and/or amino acid sequence disclosed in the international application, the							
	Inter	national preliminary examination was carried out on the basis of the sequence listing:							
		contained in the international application in printed form.							
		filed together with the international application in computer readable form.							
		furnished subsequently to this Authority in written form.							
		furnished subsequently to this Authority in computer readable form.							
		The statement that the subsequently furnished written sequence listing does not go beyond the disclosure in the							
		international application as filed has been furnished.							
		The statement that the information recorded in computer readable form is identical to the written sequence							
list	ing	han haan furnished							
· e		has been furnished.							
4.		The amendments have resulted in the cancellation of:							
		the description, pages <u>NONE</u>							
		the claims, Nos. NONE							
		the drawings, sheets/ <del>fig</del> NONE							
5.		This report has been established as if (some of) the amendments had not been made, since they have been considered to go							
		beyond the disclosure as filed, as indicated in the Supplemental Box (Rule 70.2(c)).**							
		cement sheets which have been furnished to the receiving Office in response to an invitation under Article 14 are referred to in							
		rt as "originally filed" and are not annexed to this report since they do not contain amendments (Rules 70.16 and 70.17). eplacement sheet containing such amendments must be referred to under item 1 and annexed to this report.							

#### INTERNATIONAL PRELIMINARY EXAMINATION REPORT

Form PCT/IPEA/409 (Box V) (July 1998)

International application No. PCT/US03/39211

V. Reasoned statement under Rule 66.2(a)(ii) with regard to novelty, inventive step or industrial applicability; citations and explanations supporting such statement						
1. STATEMENT						
Novelty (N)	Claims	1-26	YES			
		NONE	NO NO			
Inventive Step (IS)	Claims		YES			
	Claims	NONE	NO			
Industrial Applicability (IA)	Claims	1-26	YES			
	Claims		NONO			
Claims 1-26 meet the criteria set out in PCT Article 3 can be made or used in industry.		is meet industrial applicability	pecause the subject matter claimed			

# HIGHLY EFFICIENT (B,A1,Ga,In)N BASED LIGHT EMITTING DIODES VIA SURFACE ROUGHENING

#### 1. Field of the Invention.

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The invention is related to light emitting diodes, and more particularly, to highly efficient (B,Al,Ga,In)N based light emitting diodes via surface roughening.

#### 2. Description of the Related Art.

(Note: This application references a number of different publications as indicated throughout the specification by one or more reference numbers. A list of these different publications ordered according to these reference numbers can be found below in the section entitled "References." Each of these publications is incorporated by reference herein.)

Gallium nitride (GaN) based wide band gap semiconductor light emitting diodes (LEDs) have been available for about 10 years. The progress of LED development has brought about great changes in LED technology, with the realization of full-color LED displays, LED traffic signals, white LEDs and so on

Recently, high-efficiency white LEDs have gained much interest as possible replacements for fluorescent lamps. Specifically, the efficiency of white LEDs (74 lm/W) [1] is approaching that of ordinary fluorescent lamps (75 lm/W). Nonetheless, more improvement in efficiency is desirable.

There are two principle approaches for improving LED efficiency. The first approach is increasing the internal quantum efficiency ( $\eta_i$ ), which is determined by crystal quality and epitaxial layer structure, while the second approach is increasing the light extraction efficiency ( $\eta_{\text{extraction}}$ ).

Increasing the internal quantum efficiency cannot readily be done. A typical  $\eta_i$  value for blue LEDs is more than 70% [2] and an ultraviolet (UV) LED grown on a low-dislocation GaN substrate has recently exhibited an  $\eta_i$  of about 80% [3]. There is little room for improvement of these values.

#### WHAT IS CLAIMED IS:

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- 1. A (B,Al,Ga,In)N based light emitting diode (LED), wherein light is extracted through a nitrogen face (N-face) of the LED and a surface of the N-face is roughened.
  - 2. The LED of claim 1, wherein the surface of the N-face is roughened into one or more cones.
- The LED of claim 1, wherein the roughened surface reduces light reflections occurring repeatedly inside the LED, and thus extracts more light out of the LED.
- 4. The LED of claim 1, wherein the surface of the N-face is roughened by an anisotropic etching.
  - 5. The LED of claim 4, wherein the anisotropic etching is a dry etching.
- 6. The LED of claim 4, wherein the anisotropic etching is a photo-20 enhanced chemical (PEC) etching.
  - 7. The LED of claim 1, wherein the N-face is an n-type layer of the LED.
- 8. The LED of claim 1, wherein the N-face is prepared by a laser lift off (LLO) technique.
  - 9. The LED of claim 1, wherein the LED is grown on a c-plane gallium nitride (GaN) wafer and a gallium face (Ga-face) is a p-type layer.

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- The LED of claim 1, wherein the LED is comprised of an n-type 10. electrode, n-type layer, active region, p-type layer and p-type electrode.
- The LED of claim 10, wherein the n-type layer, active region and p-11. type layer are each comprised of a (B, Al, Ga, In)N alloy. 5
  - 12. The LED of claim 10, wherein the p-type electrode has a property of high reflection to decrease light absorption and to increase light reflection toward the surface of the n-type layer.

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The LED of claim 10, wherein the LED includes a current-blocking 13. layer aligned under the n-type electrode to keep the current from concentrating below the n-type electrode, so that absorption of light emission under the n-type electrode can be avoided and extraction efficiency can be increased.

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- The LED of claim 10, wherein the LED includes a current-confining 14. frame made of an insulator to restrain leakage current through the sidewalls of the LED without significantly decreasing an emitting area.
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- The LED of claim 2, wherein the roughened surface is comprised of a 15. plurality of hexagonal shaped cones that have an angle equal to or smaller than:

$$2\sin^{-1}(n_{air}/n_s)\approx 47.2^{\circ}$$

for a gallium nitride (GaN) LED, where  $n_{air}$  is a refractive index of air and  $n_s$  is a 25 refractive index of GaN.



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16. The LED of claim 2, wherein the roughened surface is comprised of a plurality of hexagonal shaped cones that have an angle equal to or smaller than:

$$2\sin^{-1}(n_{enc}/n_s)$$

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for epoxy, where  $n_{enc}$  is a refractive index of epoxy and  $n_s$  is a refractive index of the LED.

17. A method of creating a (B,Al,Ga,In)N based light emitting diode (LED), wherein light is extracted through a nitrogen face (N-face) of the LED, comprising:

roughening a surface of the N-face into one or more cones.

- 18. The method of claim 17, wherein the roughening step is performed using an anisotropic etching.
  - 19. The method of claim 18, wherein the anisotropic etching is a dry etching.
- 20. The method of claim 18, wherein the anisotropic etching is a wet etching.
  - 21. The method of claim 20, wherein the wet etching is a photo-enhanced chemical (PEC) etching.

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22. A light emitting diode (LED) comprised of an n-type electrode, n-type layer, active region, p-type layer and p-type electrode, wherein a nitrogen face (N-face) surface of the n-type layer is roughened into one or more cones and light is extracted through the roughened N-face surface of the n-type layer.

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23. The method of claim 22, wherein the N-face surface of the n-type layer is roughened using an anisotropic etching.

- 24. The method of claim 23, wherein the anisotropic etching is a dry etching.
- The method of claim 23, wherein the anisotropic etching is a wet etching.
  - 26. The method of claim 25, wherein the wet etching is a photo-enhanced chemical (PEC) etching.